# **TOSHIBA PHOTOCOUPLER**

# TLP731(D4)SERIES, TLP741(D4)SERIES

ATTACHMENT: SPECIFICATIONS FOR  $\underline{VDE0884}$  OPTION: (D4)

Types: TLP731, TLP732, TLP741G, TLP741J

Type designations for 'Option: (D4)', which are tested under VDE0884 requirements.

Ex. : TLP732 (D4-GR-LF2) D4 : VDE0884 option

GR: CTR rank LF2: lead bend

Note : Use Toshiba standard type number for safety standard application.

Ex. TLP732 (D4-GR-LF2)  $\rightarrow$  TLP732

# **VDE0884 ISOLATION CHARACTERISTICS**

DESCRIPTION	SYMBOL	RATING	UNIT
$ \begin{array}{ll} \textbf{Application Classification} \\ \textbf{(DIN VDE0109/12.83, Table 1)} \\ \textbf{for rated mains voltage} & \leq 300 V_{rms} \\ \textbf{for rated mains voltage} & \leq 600 V_{rms} \\ \end{array} $		I-IV I-III	_
Climatic Classification (DIN IEC68 Teil 1/09.80)		55/100/21	_
Pollution Degree (DIN VDE0109 / 12.83)		2	_
Maximum Operating Insulation Voltage	$v_{IORM}$	630	Vpk
Input to output Test Voltage, Method A  Vpr=1.2×V <sub>IORM</sub> , Type and Sample Test tp=60s, Partial Discharge<5pC	Vpr	760	Vpk
Input to output Test Voltage, Method B  Vpr=1.6×V <sub>IORM</sub> , 100% Production Test tp=1s, Partial Discharge<5pC	Vpr	1000	Vpk
Highest Permissible Overvoltage (Transient Overvoltage, $t_{pr}=10s$ )	$v_{ m TR}$	6000	Vpk
Safety Limiting Values (Max. permissible ratings in case of fault, also refer to thermal derating curve)			
Current (Input current I <sub>F</sub> , P <sub>Si</sub> =0)	$I_{si}$	400	mA
Power (Output or Total Power Dissipation) Temperature	$egin{array}{c}  ext{P}_{ ext{si}} \  ext{T}_{ ext{si}} \end{array}$	700 150	$^{ m mW}$
Insulation Resistance at Tsi, V <sub>IO</sub> =500V	$R_{si}$	$\geq$ $10^{9}$	Ω

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### **INSULATION RELATED SPECIFICATIONS**

		7.62mm pitch standard type	10.16mm pitch (LF2) type
Minimum Creepage Distance (*)	Cr	7.0mm	8.0mm
Minimum Clearance (*)	Cl	7.0mm	8.0mm
Minimum Insulation Thickness	ti	0.5mm	
Comperative Tracking Index	CTI	175	
(DIN IEC112/VDE0303, Part 1)		(VDE0109/12.83 Group <b>Ⅲ</b> a)	

- ((\*) in accordance with DIN VDE0109/12.83, Table 2, & 4)
  - (\*1) If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value (e. g. at a standard distance between soldering eye centres of 7.5mm). If this is not permissible, the user shall take suitable measures.
  - (\*2) This photocoupler is suitable for 'safe electrical isolation' only within the safety limit data.

Maintenance of the safety data shall be ensured by means of protective circuits.

VDE Test sign: Marking on product

for VDE0884



Marking on packing for VDE0884



0884

Figure 1 Partial discharge measurement procedure according to VDE0884 Destructive test for qualification and sampling tests.

#### Method A

(for type and sampling tests, destructive tests)

$$\begin{array}{lll} t_1, \ t_2 & = 1 \ to \ 10s \\ t_3, \ t_4 & = 1s \\ t_P \ (\text{Measuring time for} \\ & \text{partial discharge}) \ = 50s \\ t_b & = 62s \\ t_{\text{ini}} & = 10s \end{array}$$

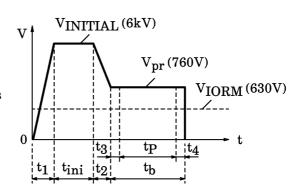
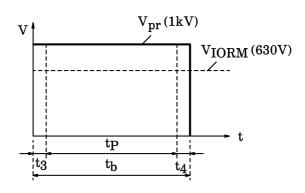


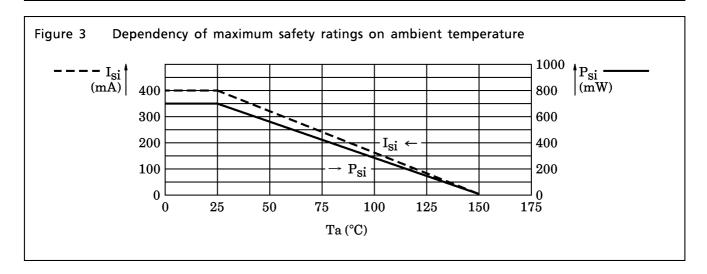
Figure 2 Partial discharge measurement procedure according to VDE0884 Non-destructive test for 100% inspection.

#### Method B

(for sample test, non-destructive test)

$$t_3$$
,  $t_4$  = 0.1s  
 $t_P$  (Measuring time for  
partial discharge) = 1s  
 $t_h$  = 1.2s





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